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## Contents

### SESSION 1

<table>
<thead>
<tr>
<th>Paper ID</th>
<th>Title</th>
<th>Authors</th>
</tr>
</thead>
<tbody>
<tr>
<td>8659 02</td>
<td>Fundamental performance differences of CMOS and CCD imagers: part V</td>
<td>J. R. Janesick, T. Elliott, J. Andrews, J. Tower, J. Pinter, SRI International Sarnoff (United States)</td>
</tr>
<tr>
<td>8659 03</td>
<td>Kirana: a solid state megapixel uCMOS image sensor for ultra-high speed imaging</td>
<td>J. Crooks, B. Marsh, R. Turchetta, Rutherford Appleton Lab. (United Kingdom); K. Taylor, W. Chan, Specialised Imaging Ltd. (United Kingdom); A. Lahav, A. Fenigstein, Tower Semiconductor, Ltd. (Israel)</td>
</tr>
<tr>
<td>8659 04</td>
<td>Back-side-illuminated image sensor with burst capturing speed of 5.2 Tpixel per second</td>
<td>T. Arai, J. Yonai, T. Hayashida, H. Ohtake, NHK Science &amp; Technical Research Labs. (Japan); H. van Kuijk, Teledyne DALSA (Netherlands); T. G. Etoh, Ritsumeikan Univ. (Japan)</td>
</tr>
</tbody>
</table>

### SMART SENSORS

<table>
<thead>
<tr>
<th>Paper ID</th>
<th>Title</th>
<th>Authors</th>
</tr>
</thead>
<tbody>
<tr>
<td>8659 05</td>
<td>A custom CMOS imager for multi-beam laser scanning microscopy and an improvement of scanning speed</td>
<td>M.-W. Seo, K. Kagawa, K. Yasutomi, S. Kawahito, Shizuoka Univ. (Japan)</td>
</tr>
<tr>
<td>8659 06</td>
<td>An ultrafast ultracompact sensor for diffuse wave spectroscopy</td>
<td>K. Barjean, D. Ettori, E. Tinet, Lab. de Physique des Lasers, CNRS, Univ. Paris 13 (France); A. Dupret, CEA-LETI MINATEC (France); M. Vasiliiu, Institut d’Electronique Fondamentale, CNRS, Univ. Paris-Sud 11 (France); J.-M. Tualle, Lab. de Physique des Lasers, CNRS, Univ. Paris 13 (France)</td>
</tr>
<tr>
<td>8659 07</td>
<td>A 3D image sensor with adaptable charge subtraction scheme for background light suppression</td>
<td>J. Shin, B. Kang, K. Lee, J. D. K. Kim, Samsung Advanced Institute of Technology (Korea, Republic of)</td>
</tr>
<tr>
<td>8659 08</td>
<td>High performance 7.4-micron interline transfer CCD platform for applied imaging markets</td>
<td>D. A. Carpenter, J. A. DiBella, R. Kaser, B. Kecskemety, S. L. Kosman, J. P. McCarten, C. Parks, Truesense Imaging, Inc. (United States)</td>
</tr>
</tbody>
</table>
HIGH-PERFORMANCE SENSORS

8659 09  A 33M-pixel wide color gamut image capturing system using four CMOS image sensors at 120 Hz [8659-8]

8659 0A  A 3Mpixel ROIC with 10µm pixel pitch and 120Hz frame rate digital output [8659-9]

8659 0B  Dynamic capability of sensors with nonlinear pixels utilized by security cameras [8659-11]
A. Johannesson, H. Eliasson, S. Fors, Axis Communications AB (Sweden)

NOISE AND CHARACTERIZATION

8659 0C  Empirical formula for rates of hot pixel defects based on pixel size, sensor area, and ISO [8659-13]
G. H. Chapman, R. Thomas, Simon Fraser Univ. (Canada); Z. Koren, I. Koren, Univ. of Massachusetts, Amherst (United States)

8659 0D  A statistical evaluation of low frequency noise of in-pixel source follower-equivalent transistors with various channel types and body bias [8659-14]
R. Kuroda, A. Yonezawa, A. Teramoto, T.-L. Li, Y. Tochigi, S. Sugawa, Tohoku Univ. (Japan)

8659 0E  New analog readout architecture for low noise CMOS image sensors using column-parallel forward noise-canceling circuitry [8659-15]
T. –L. Li, Y. Goda, S. Wakashima, R. Kuroda, S. Sugawa, Tohoku Univ. (Japan)

8659 0F  A novel pixel design with hybrid type isolation scheme for low dark current in CMOS image sensor [8659-16]
S. H. Choi, Sungkyunkwan Univ. (Korea, Republic of) and SAMSUNG Electronics Co., Ltd. (Korea, Republic of); Y. T. Kim, M. S. Oh, Y. H. Park, J. J. Cho, Y. H. Jang, H. J. Han, J. W. Choi, H. W. Park, S. I. Jung, H. S. Oh, J. C. Ahn, H. Goto, C. Y. Choi, SAMSUNG Electronics Co., Ltd. (Korea, Republic of); Y. Roh, Sungkyunkwan Univ. (Korea, Republic of)

TECHNOLOGICAL IMPROVEMENTS

8659 0G  Continuous fabrication technology for improving resolution in RGB-stacked organic image sensor [8659-17]
T. Sakai, H. Seo, S. Aihara, M. Kubota, NHK Science and Technology Research Labs. (Japan); M. Furuta, Kochi Univ. of Technology (Japan)
Biological tissue identification using a multispectral imaging system [8659-18]
C. Delporte, Univ. Pierre et Marie Curie (France) and Lab. d’Electronique et Electromagnétisme, UR2, Univ. Pierre et Marie Curie (France); S. Sautrot, Univ. Denis Diderot (France) and Lab. d’Electronique et Electromagnétisme, UR2, Univ. Pierre et Marie Curie (France); M. Ben Chouikha, Univ. Pierre et Marie Curie (France) and Lab. d’Electronique et Electromagnétisme, UR2, Univ. Pierre et Marie Curie (France); F. Viénot, Muséum National d'Histoire Naturelle (France); G. Alquié, Univ. Pierre et Marie Curie (France) and Lab. d’Electronique et Electromagnétisme, UR2, Univ. Pierre et Marie Curie (France)

A CMOS image sensor using floating capacitor load readout operation [8659-19]
S. Wakashima, Y. Goda, T. -L. Li, R. Kuroda, S. Sugawa, Tohoku Univ. (Japan)

A UV Si-photodiode with almost 100% internal Q.E. and high transmittance on-chip multilayer dielectric stack [8659-20]
Y. Koda, R. Kuroda, T. Nakazawa, Y. Nakao, S. Sugawa, Tohoku Univ. (Japan)

APPLICATIONS

High sensitivity analysis of speckle patterns: a technological challenge for biomedical optics (Invited Paper) [8659-21]
J.-M. Tualle, K. Barjean, E. Tinet, D. Ettori, Lab. de Physique des Lasers, CNRS, Univ. Paris 13 (France)

Gesture recognition on smart cameras [8659-22]
A. Dziri, S. Chevobbe, M. Darouch, CEA LIST (France)

3DS-colorimeter based on a mobile phone camera for industrial applications [8659-23]
J. Miettinen, VTT Technical Research Ctr. of Finland (Finland); J. B. Martinkauppi, Univ. of Vaasa (Finland); P. Suopajärvi, VTT Technical Research Ctr. of Finland (Finland)

A single lens with no moving parts for rapid, high-resolution, 3D image capture [8659-24]

Measurement and description method for image stabilization performance of digital cameras [8659-25]
N. Aoki, Nikon Corp. (Japan); H. Kusaka, Panasonic Corp. (Japan); H. Otsuka, Canon Inc. (Japan)

Interconnected network of cameras [8659-26]

INTERACTIVE PAPER SESSION

Creation of North-East Indian face database for human face identification [8659-29]
K. Saha, P. Saha, M. K. Bhowmik, Tripura Univ. (India); D. Bhattacharjee, M. Nasipuri, Jadavpur Univ. (India)
Optical characterization parameters by study and comparison of subwavelength patterns for color filtering and multispectral purpose [8659-30]
J. Matanga, Lab. Electronique, Informatique et Image, CNRS, Univ. de Bourgogne (France); Y. Lacroute, Lab. Interdisciplinaire Carnot de Bourgogne, CNRS, Univ. de Bourgogne (France); P. Gouton, Lab. Electronique, Informatique et Image, CNRS, Univ. de Bourgogne (France); E. Bourillot, Lab. Interdisciplinaire Carnot de Bourgogne, CNRS, Univ. de Bourgogne (France)

Characterization of a solid state air corona charging device [8659-28]
M. Young, B. Xu, S. Buhler, K. Littau, Palo Alto Research Ctr., Inc. (United States)

Author Index
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  Franz Riedlberger, TowerJazz (Germany)
  Nobukazu Teranishi, Panasonic Corporation (Japan)
  Xinyang Wang, Chinese Academy of Sciences (China)

Session Chairs
  1 Session 1
     Ralf Widenhorn, Portland State University (United States)
  2 Smart Sensors
     Arnaud Darmont, Aphesa SPRL (Belgium)
  3 High-Performance Sensors
     Kevin J. Matherson, Microsoft Corporation (United States)
  4 Noise and Characterization
     Boyd A. Fowler, BAE Systems Imaging Solutions (United States)
Technological Improvements
Antoine Dupret, CEA LETI MINATEC (France)

Applications
Alice L. Reinheimer, e2v (United States)